

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

TSSOP Exp. Pad

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**TOTAL MASS (g) : 0.098882**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005720	1000000	57846.515625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.030596	975000	309418.1875		
		Iron (Fe)	7439-89-6	0.000753	24000	7615.109375		
		Phosphorus (P)	7723-14-0	0.000009	300	91.017250061		
		Zinc (Zn)	7440-66-6	0.000022	700	222.486618042		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.031380</b>	<b>1000000</b>	<b>317346.8125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002480	1000000	25083.8886719		
		<b>External Plating Total:</b>				<b>0.002480</b>	<b>1000000</b>	<b>25083.8886719</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000806	1000000	8151.10107422		
<b>Internal Plating Total:</b>				<b>0.000806</b>	<b>1000000</b>	<b>8151.10107422</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001470	750000	14866.1513672		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000490	250000	4955.38330078		
<b>Die Attach Total:</b>				<b>0.001960</b>	<b>1000000</b>	<b>19821.5332031</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.007460	135000	75443.1875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.047524	860000	480611.53125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000276	5000	2791.19555664		
		<b>Encapsulation Total:</b>				<b>0.055260</b>	<b>1000000</b>	<b>558845.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001276	1000000	12904.2236328		
<b>TOTAL MASS (g) :</b>						<b>0.098882</b>		